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CONTAINER WITH IC PART

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Abstract of JP2001334530

PROBLEM TO BE SOLVED: To provide a method capable of recycling (recovering) tableware with an IC part wherein the IC part is strongly bonded to a tableware main body by a thermosetting adhesive.

SOLUTION: The method for recycling the tableware 18 with the IC part wherein the IC part 14, wherein an IC substrate is covered with a plastic material, is provided on the predetermined region of the tableware main body 12 made of a plastic material through an adhesive layer 16 is disclosed. The adhesive layer 16 having a thickness of 0.5 mm or more is formed from an elastic adhesive with an elongation (EB; JIS K6301) of 180% or more and/or a hardness (Shore A) of 50 or less. The separation of the IC part 14 from the tableware main body 12 is performed by cutting the region of the adhesive layer 16 by mechanical force. Then, the IC part is immersed in an adhesive dissolving agent which is prepared by adding a surfactant to an organic solvent as a permeability enhancer to swell and dissolve the remaining adhesive layer to peel and remove the same from the IC part.

